

EXPRESS MAIL LABEL NO.: EV343426451US

COOLING OF SURFACE TEMPERATURE OF A DEVICE

ABSTRACT OF THE INVENTION

A structure (microduct) for temperature management (e.g., cooling) of the surface temperature of an electronic device (e.g., a microprocessor). In an embodiment of the present invention, the system includes an upper plate, wherein the upper plate has a bottom surface forming the top portion and sides of the microduct structure, and wherein the top surface of a lower wall forms the bottom surface of the microduct structure. The lower wall can be adapted to be coupled to a top surface of device. The microduct structure further includes a coolant that flows through the microduct to provide cooling for a device.

160-p0008v3.doc